

Filed on behalf of: Yangtze Memory Technologies Company, Ltd.

Entered on: April 20, 2026

UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE PATENT TRIAL AND APPEAL BOARD

MICRON TECHNOLOGY, INC.,
Petitioner,

v.

YANGTZE MEMORY TECHNOLOGIES COMPANY, LTD.,
Patent Owner.

Case IPR2025-00228
Patent 11,101,276

PATENT OWNER'S UPDATED EXHIBIT LIST

Pursuant to 37 C.F.R. § 42.63(e), Patent Owner respectfully submits the following updated Exhibit List:

Ex.	Description
2001	Defendants' Preliminary Invalidity Contentions and Document Production Accompanying Invalidity Contentions re YMTC II Asserted Patents (Patent Local Rules 3-3 and 3-4), <i>Yangtze Memory Technologies Company, Ltd. v. Micron Technology, Inc.</i> , No. 3:23-cv-05792-RFL (N.D. Cal. Nov. 25, 2024) (excerpts)
2002	Civil Minutes, <i>Yangtze Memory Technologies Company, Ltd. v. Micron Technology, Inc.</i> , No. 3:23-cv-05792-RFL (N.D. Cal. Sept. 18, 2024), ECF No. 141
2003	Order Granting Stipulation to Extend Certain Deadlines Pursuant to Patent L.R. 4-2 and the Scheduling Order (ECF No. 141) Pursuant to Civil Local Rule 6-1(b), <i>Yangtze Memory Technologies Company, Ltd. v. Micron Technology, Inc.</i> , No. 3:23-cv-05792-RFL (N.D. Cal. Jan. 8, 2025), ECF No. 194
2004	Order Granting Motion to Stay Case Pending <i>Inter Partes</i> Review, <i>Yangtze Memory Technologies Company, Ltd. v. Micron Technology, Inc.</i> , No. 3:23-cv-05792-RFL (N.D. Cal. Mar. 14, 2025), ECF No. 243
2005	Plaintiff/Counterclaim Defendant Yangtze Memory Technologies Company, Ltd.'s and Counterclaim Defendant Yangtze Memory Technologies, Inc.'s Opposition to Micron's Motion to Stay Case Pending <i>Inter Partes</i> Review and Post-Grant Proceedings, <i>Yangtze Memory Technologies Company, Ltd. v. Micron Technology, Inc.</i> , No. 3:23-cv-05792-RFL (N.D. Cal. Feb. 3, 2025), ECF No. 221
2006	Declaration of Stephen Campbell in Support of Patent Owner's Preliminary Response ("Campbell")
2007	<i>Curriculum Vitae</i> of Stephen Campbell

Ex.	Description
2008-2017	RESERVED
2018	Order Granting Motion to Consolidate, <i>Yangtze Memory Technologies Company, Ltd. v. Micron Technology, Inc.</i> , No. 3:23-cv-05792-RFL (N.D. Cal. Aug. 21, 2024), ECF No. 106
2019	Declaration of Steve Campbell in Support of Patent Owner's Response ("Campbell2")
2020	Transcript of the Deposition of Sanjay Banerjee, Ph.D., taken October 2, 2025, <i>Micron Tech., Inc. v. Yangtze Memory Techs. Co.</i> , IPR2025-00228 (Patent No. 11,101,276)
2021	Transcript of the Deposition of Sanjay Banerjee, Ph.D., taken August 13, 2025, <i>Micron Tech., Inc. v. Yangtze Memory Techs. Co.</i> , IPR2025-00117 (Patent No. 10,672,711)
2022	<i>3D Flash Memories</i> (Rino Micheloni ed., 2016)
2023	Harmeet Singh, <i>Overcoming Challenges in 3D NAND Volume Manufacturing</i> , 60 Solid State Tech. 18 (July 2017) (excerpt)
2024	Thermo Fisher Scientific, <i>White Paper: The Challenge of Measuring Buried Critical Dimensions in High-Aspect-Ratio Structures: How Busy Fab Process Owners Can Reduce Time-to-Data in 3D NAND Metrology</i> , https://assets.thermofisher.com/TFS-Assets/MSD/Reference-Materials/helios-5-pxl-3d-nand-whitepaper-wp0025.pdf (last visited Aug. 5, 2025)
2025	Mark Lapedus, <i>What's Next for NAND?: Vendors Pin Hopes on 3D Memory, Raising Specter of 2D NAND Shortages; Other Memory Types Add to Uncertainty</i> , Semiconductor Eng'g (May 19, 2016), https://web.archive.org/web/20161127122539/https://semiengineering.com/whats-next-for-nand/ (last visited Aug. 15, 2025)

Ex.	Description
2026	Mark Shirey & Janay Camp, <i>Digging Deep Into High Aspect Ratio Process Control for Memory Technology</i> , Semiconductor Eng'g (Oct. 18, 2018), https://web.archive.org/web/20250621011306/https://semiengineering.com/digging-deep-into-high-aspect-ratio-process-control-formemory-technology/ (last visited Aug. 15, 2025)
2027	Mark Lapedus, <i>3D NAND Flash Wars Begin: Market Overcrowding, More Efficient Manufacturing, and Growing List of Scaling Issues Create a Challenging Competitive Landscape</i> , Semiconductor Eng'g (Aug. 20, 2018), https://web.archive.org/web/20180822030129/https://semiengineering.com/3d-nand-flash-wars-begin/ (last visited Aug. 15, 2025)
2028	Mark Lapedus, <i>3D NAND Metrology Challenges Growing: Rising Costs and Gaps in Equipment Emerge as Technology Scales; New Tools Under Development</i> , Semiconductor Eng'g (Apr. 9, 2019), https://semiengineering.com/3d-nand-metrology-challenges-growing/ (last visited Aug. 15, 2025)
2029	Mark Lapedus, <i>3D NAND's Vertical Scaling Race: More Competition, Business Uncertainty, and Much More Difficult Manufacturing Processes</i> , Semiconductor Eng'g (Dec. 17, 2020), https://semiengineering.com/3d-nands-vertical-scaling-race/ (last visited Aug. 15, 2025)
2030	Stephen A. Campbell, <i>Fabrication Engineering at the Micro- and Nanoscale</i> 297 (Adel S. Sedra ed., 4th ed. 2013) (excerpt)
2031	Declaration of Benjamin Smith In Response To Petitioner's Objections to Evidence [<i>served only</i>]
2032	Declaration of Robert B. Dunteman In Support of Patent Owner's Unopposed Motion for <i>Pro Hac Vice</i> Admission Under 37 C.F.R. § 42.10(c)
2033	Declaration of Benjamin Smith In Response To Petitioner's Objections to Evidence, with Appendices A-N [<i>served only</i>]

Ex.	Description
2034	Patent Owner's Demonstratives

Respectfully submitted,

Dated: April 20, 2026

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CERTIFICATE OF SERVICE

Pursuant to 37 C.F.R. § 42.6(e), I certify that on this 20th day of April, 2026, a true and correct copy of the foregoing **Patent Owner's Updated Exhibit List and Exhibit 2034** were served by electronic mail on Petitioner's lead and backup counsel at the following email addresses:

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